

## POE PCB Manufacture Capability

Item	Capability			
1. Base Material	FR-4 / High TG FR-4 / Lead free Materials (ROHS Compliant) / Halogen Free material /CEM-3/CEM-1/ /PTFE/ROGERS/ARLON/TACONIC			
2. Layers	1-28layer			
3. Finised inner/outer copper thickness	1-6OZ			
4. Finished board thickness	0.2-7.0mm			
	<table border="1" style="width: 100%;"> <tr> <td style="width: 15%;">Tolerance</td> <td>                     Board thickness ≤ 1.0mm: +/-0.1mm                      1 &lt; Board thickness ≤ 2.0mm: +/-10%                      Board thickness &gt; 2.0mm: +/-8%                 </td> </tr> </table>	Tolerance	Board thickness ≤ 1.0mm: +/-0.1mm 1 < Board thickness ≤ 2.0mm: +/-10% Board thickness > 2.0mm: +/-8%	
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5. Max panel size	≤ 2sides PCB: 600*1500mm Multilayer PCB: 500*1200mm			
6. Min conductor line width/spacing	Inner layers: ≥ 3/3mil Outer layers: ≥ 3.5/3.5mil			
7. Min hole size	Mechanical hole: 0.15mm Laser hole: 0.1mm			
	<table border="1" style="width: 100%;"> <tr> <td style="width: 15%;">Drilling precision: first drilling</td> <td>First drilling: 1mil</td> </tr> <tr> <td>Second drilling</td> <td>Second drilling: 4mil</td> </tr> </table>	Drilling precision: first drilling	First drilling: 1mil	Second drilling
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Second drilling	Second drilling: 4mil			
8. Warpage	Board thickness ≤ 0.79mm: β ≤ 1.0% 0.80 ≤ Board thickness ≤ 2.4mm: β ≤ 0.7% Board thickness ≥ 2.5mm: β ≤ 0.5%			
9. Controlled Impedance	+/-5%			
10. Aspect Ratio	15:01			
11. Min welding ring	4mil			
12. Min solder mask bridge	≥ 0.08mm			
13. Plugging vias capability	0.2-0.8mm			
14. Hole tolerance	PTH: +/-3mil NPTH: +/-2mil			

15.Outline profile	Rout/ V-cut/ Bridge/ Stamp hole
16.Surface treatment	OSP: 0.5-0.5um HASL: 2-40um Lead free HASL: 2-40um ENIG: Au 1-10U" ENEPIG: PB 2-5U"/ Au 1-8U" Immersion Tin:0.8-1.2um Immersion silver: 0.1-1.2um Peelable blue mask Carbon ink Gold plating: Au 1-150U"
17. E-testing pass percent	97% pass for the first time, +/-2%(tolerance) FOC-Physical Lab: Reliability tests
18.Certificate	ROHS UL:E327776 ISO9001:2008 IPC SGS
<b>Our equipments</b>	
1.Drilling workshop	4 drilling bits of drilling machine: 4 sets 2 drilling bits of drilling machine: 2 sets
2. photo plotting workshop	Israel "ORBOTECH" Photo Plotters
3.AOI	AOI machine
4.IPQC	"OXFORD" CMI 700 Copper Thickness Tester
5.Impedance test	USA "Tektronix" DSA 8200 Impedance Tester
6.Outline workshop	CNC routing machine: 7 sets angle-cutting machine V-cut machine
7.Testing Workshop	Surpass X-600: 2sets WTD FT-2808: 5sets WTD HV300: 1set
8.X-ray	X-ray machine
<b>Acceptable file format</b>	
GERBER file, PROTEL series, PADS series, POWER PCB series, AutoCAD series.	